

# Hardware User Manual

**EXT-SBC-i.MX51-DISP V1.2**

*...maximum performance at minimum space*

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#### **Information**

For further information on technology, delivery terms and conditions and prices please contact Bluetechnix (<http://www.bluetechnix.com>).

#### **Warning**

Due to technical requirements components may contain dangerous substances.

## **i.MX Core Modules**

### **CM-i.MX27-C-C-Q26S128F32N512**

The Core Module CM-i.MX27 is powered by Freescales' SoC i.MX27 (ARM 926 core, up to 400MHz). It addresses 128MB DDR-RAM, has an onboard NOR-flash of 32MByte and a NAND-flash with 512MByte at a size of 55x45mm.

### **CM-i.MX31-C-C-Q26S128F40N128-E**

The Core Module CM-i.MX31 is powered by Freescales' SoC i.MX31 (ARM1136JF-S core, up to 532MHz). It addresses 128MB DDR-RAM, has an onboard NOR-flash of 40MByte and a NAND-flash with 128MByte at a size of 55x45mm. Core module is available as connector or BGA.

### **CM-i.MX53-C-I-Q24S1024F4N2048**

The Core Module CM-i.MX53 is powered by Freescales' SoC i.MX53 (ARM® Cortex™-A8, up to 1GHz). It addresses 1024MB DDR2-SDRAM, has an onboard NOR-flash of 4MByte and a NAND-flash with 2048MByte at a size of 80x45mm.

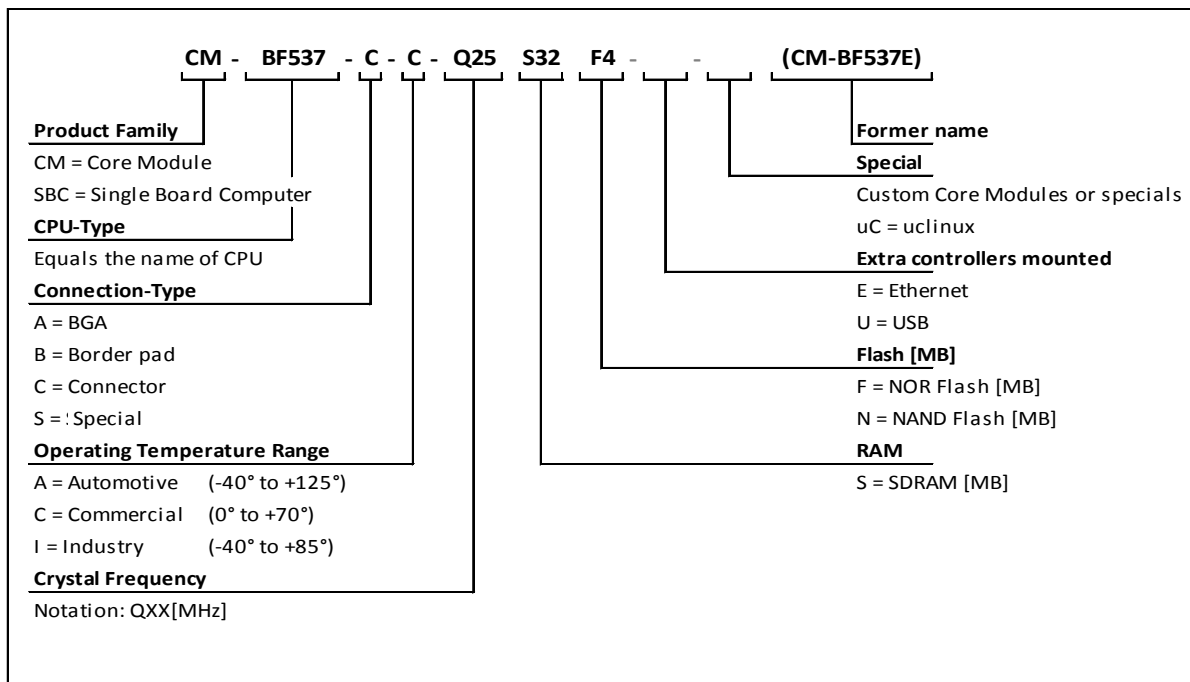
## Core Module naming information

The idea is to put more Core Module specific technical information into the product name. New Core Module names will have following technical information covered in their names.

- Product Family,
- CPU-Type,
- Connection-Type,
- Operating Temperature Range,
- Crystal Frequency [MHz],
- RAM [MB],
- Flash [MB],
- External Controllers
- Optional
  - Special and/or
  - Former name

That expands of course the name but allows the customer to get the most important Core Module specific information at the first sight. Have a look at the example below to get an idea of the new Core Module names.

### Example CM-BF537-C-C-Q25S32F4 (CM-BF537E)



## i.MX Development Boards

### [DEV-i.MX27](#)

The DEV-i.MX27 development board is an extendable development platform for the CM-i.MX27 processor modules. With display connector and keypad it can be used as a reference design for a low power mobile handheld device powered by a single Lithium Ion battery. The development board provides all interfaces of the connector version on dedicated expansion connectors. Extender boards can be plugged on top of the development board in order to enable additional interfaces.

### [DEV-iMX31](#)

The DEV-i.MX31 Development Board is an extendable development platform for the CM-i.MX31 processor module. With display connector and keypad it can be used as a reference design for a low power mobile handheld device powered by a single Lithium Ion battery. The development board provides all interfaces of the connector version on dedicated expansion connectors. Extender boards can be plugged on top of the development board in order to enable additional interfaces.

### [SBC-i.MX51-S-C-Q24S512N2048](#)

The Single-Board Computer SBC-i.MX51 is based on Freescale's high-performance i.MX51 mobile platform, incorporating an ARM Cortex-A8 CPU, an Image Processing Unit (IPUv3EX), a Video Processing Unit (VPU) and a Graphical Processing Unit (GPU). The IPUv3EX provides comprehensive support for connectivity to displays and cameras. The VPU supports hardware encoding and decoding of MPEG-4, H.263, H.264 and many more standards. The GPU serves 3D and 2D acceleration in hardware. The board's memory capabilities (NAND Flash, DDR2) and numerous interfaces like Ethernet, HDMI, 4xUSB and USB-OTG turn the SBC-i.MX51 into the ultimate development board for future high-end embedded devices.

### [DEV-i.MX53](#)

The DEV-i.MX53 development board is an extendable development platform for the CM-i.MX53 processor module. The development board provides all interfaces of the connector version (Ethernet, HDMI, 4xUSB and USB-OTG) on dedicated extender connectors. Extender boards can be plugged on top of the development board in order to enable additional interfaces.

### [Extender boards](#)

Extender boards (EXT-SBC-i.MX51-) are expanding the development board SBC-i.MX51 by several interfaces and functionalities. Targeted application areas are: audio/video processing, security and surveillance, Ethernet access, positioning, automation and control, experimental development and measuring.

Note! Bluetechnix is offering tailored board developments as well.



## 1 Introduction

The EXT-SBC-i.MX51-DISP is a pluggable extender board for the SBC-i.MX51. It offers a display and a camera interface (BLT-ISM-Connector) for the SBC-i.MX51. It is a low cost extender board designed for audiovisual systems e.g. HMI, touch-control, interactive systems etc

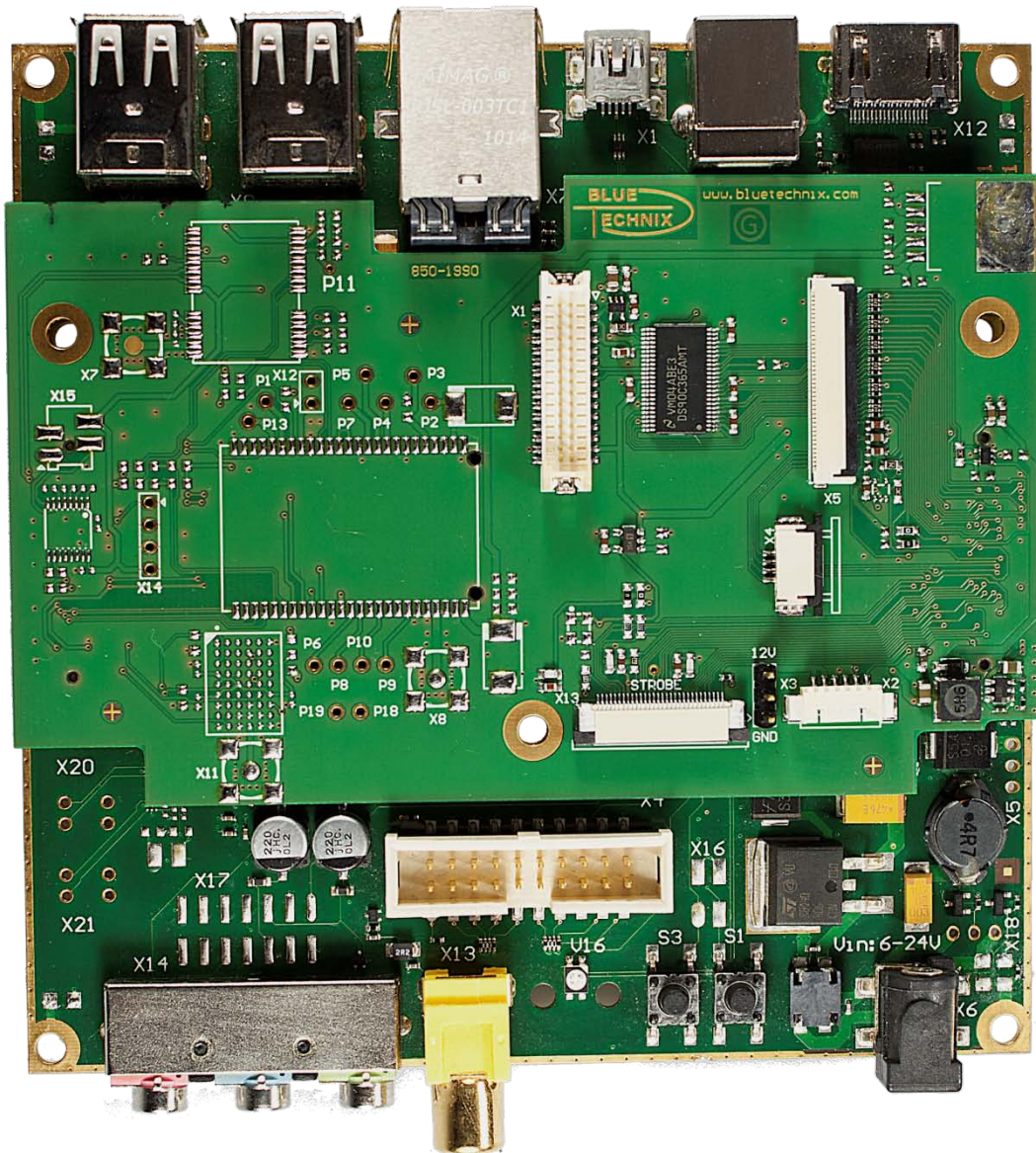


Figure 1-1: Connected EXT-SBC-i.MX51-DISP on SBC-i.MX51

## 1.1 Overview

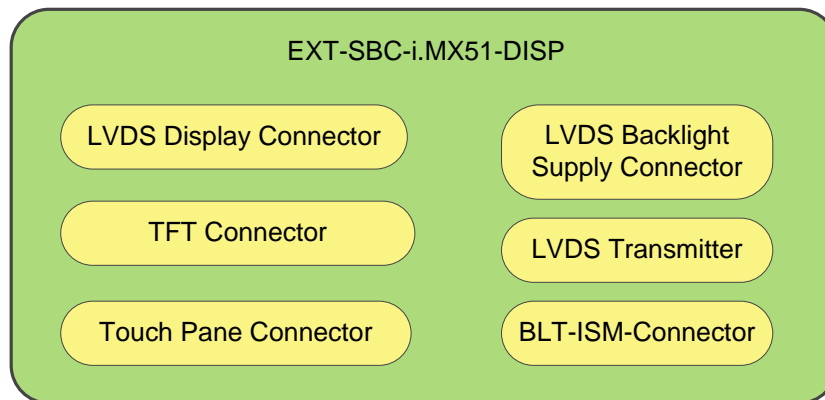


Figure 1-2: Main components of EXT-SBC-i.MX51-DISP

## 1.2 Key Features

- **TFT Connector**
  - 40 pin ZIF connector
  - Various EDT displays available (3,5" to 7"; 320x240 to 800x480)
- **LVDS Connector**
  - 30 pin connector
  - Supports Toshiba LT084AC3711 LVDS display
- **LVDS Transmitter**
  - National Semiconductor DS90C365
- **Touch Panel Connector**
  - 4 pin Connector for connection of a resistive Touch Panel
- **Power Supply**
  - LVDS Backlight supplied via separate external power supply (not included)
  - EXT-SBC-i.MX51-DISP is powered via SBC-i.MX51
- **Camera Connector (BLT-ISM-Connector)**
  - 30 pin ZIF connector
  - Compatible with all Bluetechnix [Image Sensor Modules](#)

## 1.3 Applications

- Rapid prototyping
- POS terminals
- Automation and control systems
- Graphical User Interfaces

## 2 General Description

### 2.1 Functional Description

#### 2.1.1 Powering

The EXT-SBC-i.MX51-DISP is supplied by the SBC-i.MX51. Please consider the chapter Electrical Specifications. If an LVDS display is used (e.g. LT084AC3711) an external 12V power supply must be connected to the connector X3.

### 2.2 PCB Placement

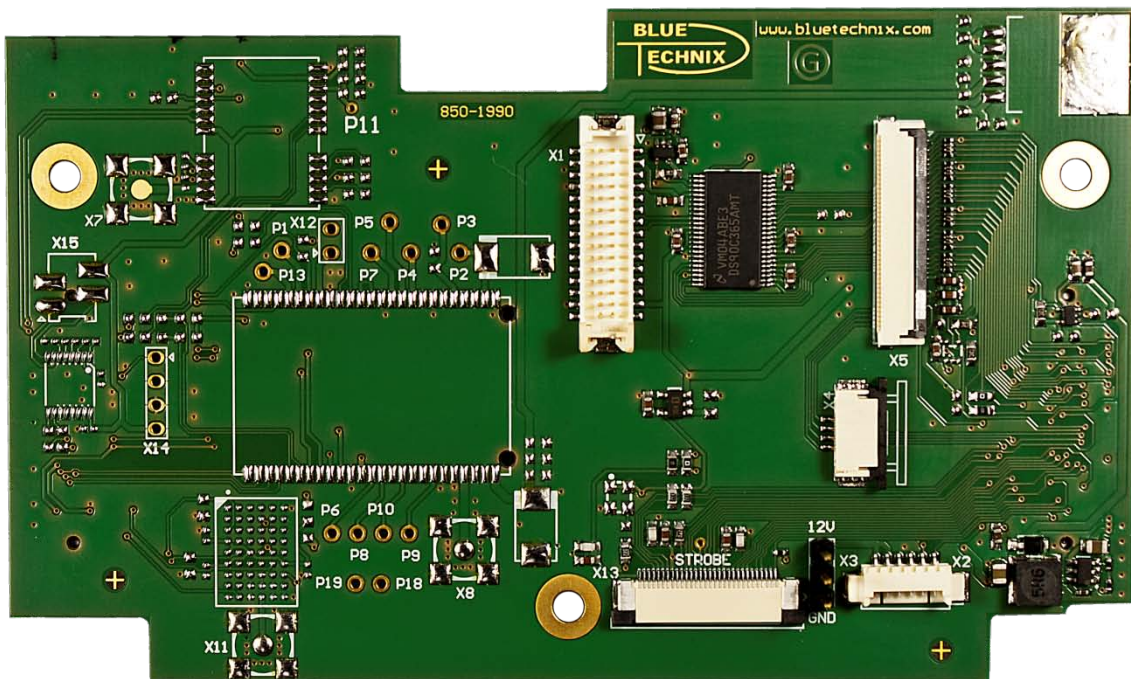


Figure 2-1: Connector positions

## 2.3 Mechanical Outline

This section shows the position of all connectors and mounting holes. All dimensions are given in mm.

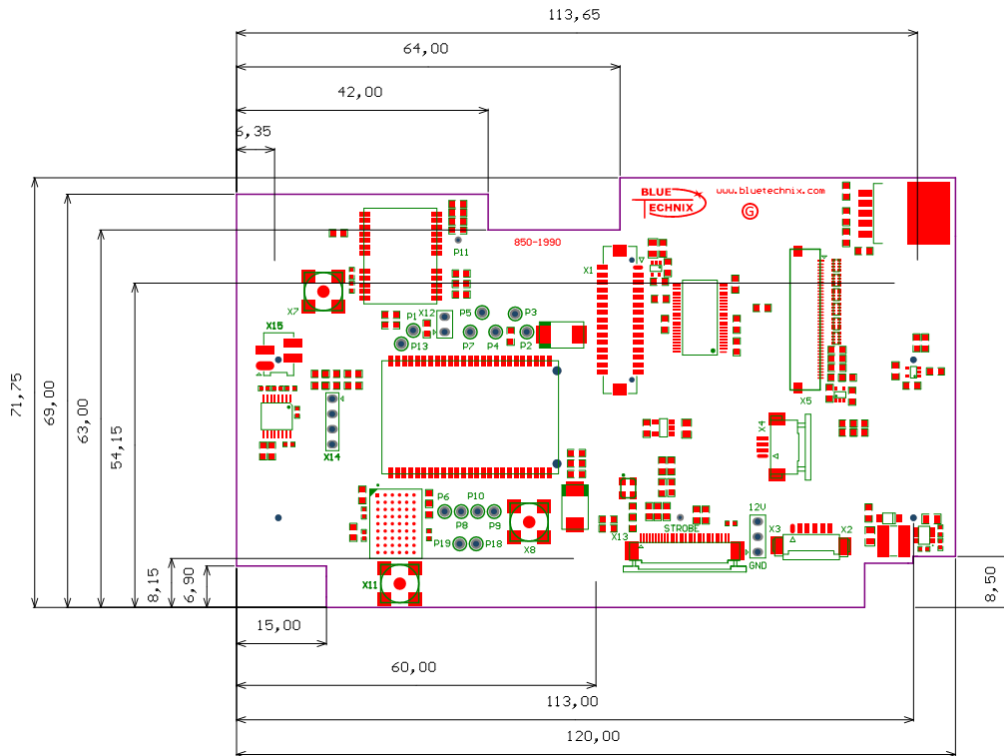


Figure 2-2: EXT-SBC-i.MX51-DISP top view

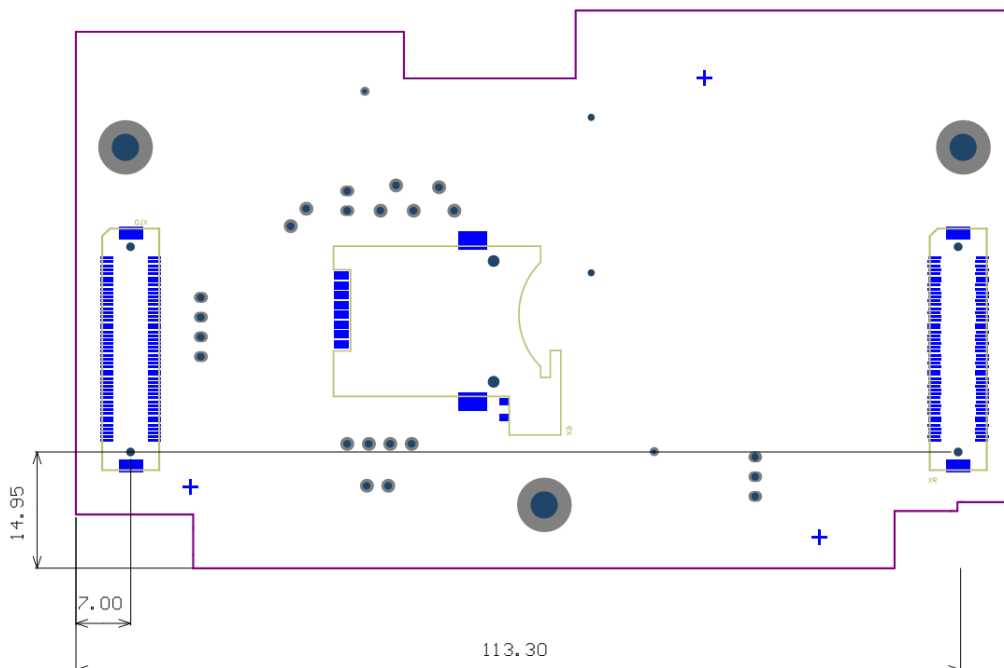


Figure 2-3: EXT-SBC-i.MX51-DISP bottom view

### 3 Specifications

#### 3.1 Electrical Specifications

##### 3.1.1 Digital I/O Characteristics

Parameter	Power Domain	Symbol	Min	Typ.	Max	Unit
High-Level Output Voltage	P_VIOHI	$V_{oh}$	2.625	2.775	3.075	V
High-Level Output Voltage	P_SW4	$V_{oh}$	1.65	1.8	2.1	V
Low-Level Output Voltage	all domains	$V_{ol}$	-	-	0.15	V
High Level Output Current	all domains	$I_{oh}$	1.9	-	6.6	mA
Low-Level Output Current	all domains	$I_{ol}$	1.9	-	6.6	mA
High-Level Input Voltage	P_VIOHI	$V_{ih}$	1.95	-	2.775	V
Low-Level Input Voltage	P_VIOHI	$V_{il}$	0	-	0.83	V
High-Level Input Voltage	P_SW4	$V_{ih}$	1.26	-	1.8	V
Low-Level Input Voltage	P_SW4	$V_{il}$	0	-	0.54	V

Table 3-1: Digital IO characteristics

##### 3.1.2 Analog Inputs

Parameter	Symbol	Min	Typ.	Max	Unit
Resolution			10		Bit
Conversion Current	$I_c$		1		mA
Conversion Core Input Voltage	$V_{in}$	0	-	2.4	V
Conversion Time Per Channel	$t_c$			10	$\mu$ s

Table 3-2: ADC characteristics

##### 3.1.3 Maximum Ratings

Stressing the device above the rating listed in the absolute maximum ratings table may cause permanent damage to the device. These are stress ratings only. Operation of the device at these or any other conditions greater than those indicated in the operating sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Symbol	Parameter	Min	Max	Unit
$V_{IO}$	Input or output voltage	-0.5	3.6	V
$V_{LED}$	Backlight supply voltage	0	20	V
$I_{OH}/I_{OL}$	Current per pin	0	10	mA
$T_{AMB}$	Ambient temperature	-20	70	$^{\circ}$ C
$T_{STO}$	Storage temperature	-55	100	$^{\circ}$ C
$T_{SLD}$	Solder temperature for 10 seconds		260	$^{\circ}$ C
$\Phi_{AMB}$	Relative ambient humidity		90	%

Table 3-3: Absolute maximum ratings

### 3.1.4 ESD Sensitivity



ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

## 4 Connector Description

### 4.1 Display Data Connector X1 (Toshiba LT084AC3711)

Pin No.	Signal Name	Type	Power Domain	Description
1	NC	NC		Not Connected
2	NC	NC		Not Connected
3	P_3V3	PWR	P_3V3	Display Power Supply
4	GND	PWR	GND	Power Ground
5	TxCLK_N	O	P_3V3	LVDS clock
6	TxCLK_P	O	P_3V3	LVDS clock
7	P_3V3	PWR	P_3V3	Display Power Supply
8	GND	PWR	GND	Power Ground
9	Tx0_N	O	P_3V3	LVDS Channel 0
10	Tx0_P	O	P_3V3	LVDS Channel 0
11	Tx1_N	O	P_3V3	LVDS Channel 1
12	Tx1_P	O	P_3V3	LVDS Channel 1
13	Tx2_N	O	P_3V3	LVDS Channel 2
14	Tx2_P	O	P_3V3	LVDS Channel 2
15	NC	NC		Not Connected
16	NC	NC		Not Connected
17	NC	NC		Not Connected
18	NC	NC		Not Connected
19	NC	NC		Not Connected
20	NC	NC		Not Connected
21	NC	NC		Not Connected
22	NC	NC		Not Connected
23	NC	NC		Not Connected
24	NC	NC		Not Connected
25	NC	NC		Not Connected
26	NC	NC		Not Connected
27	P_3V3	PWR	P_3V3	Display Power Supply
28	GND	PWR	GND	Power Ground
29	NC	NC		Not Connected
30	NC	NC		Not Connected

Table 4-1: Display Data Connector description (X1)

### 4.2 LVDS Backlight Supply Connector X2 (Toshiba LT084AC3711)

Pin No.	Signal Name	Type	Power Domain	Description
1	12V	PWR	12V	Display Power Supply
2	12V	PWR	12V	Display Power Supply
3	GND	PWR	GND	Power Ground
4	GND	PWR	GND	Power Ground
5	LVDS-nRESET	O	P_3V3	Display ON/OFF
6	PWM1	O	P_VIOHI	PWM1 Output

Table 4-2: Display Power Connector description (X2)

### 4.3 Display Power Supply Connector X3

Pin No.	Signal Name	Type	Power Domain	Description
1	12V	PWR	V_LED	External Backlight Power Supply
2	NC	NC		Not Connected
3	GND	PWR	GND	External Power Ground

Figure 4-1: Display Power Supply Connector description (X3)

### 4.4 Touch Panel Connector X4 (Toshiba LT084AC3711)

Pin No.	Signal Name	Type	Description
1	ADIN1	AI	Touch Panel XR Terminal
2	ADIN2	AI	Touch Panel YU Terminal
3	ADIN3	AI	Touch Panel XL Terminal
4	ADIN4	AI	Touch Panel YD Terminal

Figure 4-2: Touch Panel Connector description (X4)

### 4.5 Display Connector X5 (ET0500G0DH6)

Pin No.	Signal Name	Type	Power Domain	Description
1	DISP.nRESET	O	P_3V3	Display Reset
2	GND	PWR	GND	Power Ground
3	DISP2.D4	O	P_VIOHI	Blue Data Bit 5
4	DISP2.D3	O	P_VIOHI	Blue Data Bit 4
5	DISP2.D2	O	P_VIOHI	Blue Data Bit 3
6	DISP2.D1	O	P_VIOHI	Blue Data Bit 2
7	DISP2.D0	O	P_VIOHI	Blue Data Bit 1
8	DISP2.D4	O	P_VIOHI	Blue Data Bit 0
9	GND	PWR	GND	Power Ground
10	DISP2.D10	O	P_VIOHI	Green Data Bit 5
11	DISP2.D9	O	P_VIOHI	Green Data Bit 4
12	DISP2.D8	O	P_VIOHI	Green Data Bit 3
13	DISP2.D7	O	P_VIOHI	Green Data Bit 2
14	DISP2.D6	O	P_VIOHI	Green Data Bit 1
15	DISP2.D5	O	P_VIOHI	Green Data Bit 0
16	GND	PWR	GND	Power Ground
17	DISP2.D15	O	P_VIOHI	Green Data Bit 5
18	DISP2.D14	O	P_VIOHI	Green Data Bit 4
19	DISP2.D13	O	P_VIOHI	Green Data Bit 3
20	DISP2.D12	O	P_VIOHI	Green Data Bit 2
21	DISP2.D11	O	P_VIOHI	Green Data Bit 1
22	DISP2.D15	O	P_VIOHI	Green Data Bit 0
23	GND	PWR	GND	Power Ground
24	TFT.CLK	O	P_VIOHI	Dot Data Clock
25	GND	PWR	GND	Power Ground
26	TFT.HSYNC	O	P_VIOHI	Horizontal Sync
27	TFT.VSYNC	O	P_VIOHI	Vertical Sync
28	TFT.DE	O	P_3V3	Data Enable
29	TFT.PWRCTRL	O	P_VIOHI	Power Control
30	P_3V3	PWR	P_3V3	Power Supply



Pin No.	Signal Name	Type	Power Domain	Description
31	GND	PWR	GND	Power Ground
32	GND	PWR	GND	Power Ground
33	P_3V3	PWR	P_3V3	Power Supply
34	P_3V3	PWR	P_3V3	Power Supply
35	NC	NC		Not Connected
36	PWM1	O	P_VIOHI	Backlight Brightness Control
37	ADIN1	AI		Touch Panel YU Terminal
38	ADIN3	AI		Touch Panel XL Terminal
39	ADIN2	AI		Touch Panel YD Terminal
40	ADIN4	AI		Touch Panel XR Terminal

Figure 4-3: Display Connector description (X5)

## 4.6 Image Sensor Connector X13 (BLT-ISM-Connector)

Pin No.	SignalName	Type	Power Domain	Description
1	VCAMA	PWR	P_CAM_2V75	Camera Analog Voltage Supply
2	GND	PWR	GND	Power Ground
3	NC	NC		Not Connected
4	CAMCLK	O	P_SW4	Camera Master Clock
5	NRESET	O	P_SW4	Global Reset
6	SIO.C	O	P_SW4	Configuration Bus Clock Line
7	SIO.D	I/O	P_SW4	Configuration Bus Data Line
8	VCAMC	PWR	1V8	Camera Core Voltage Supply
9	GND	PWR	GND	Power Ground
10	CSI1.PCLK	I	P_SW4	Pixel Clock
11	CSI1.VSYNC	I	P_SW4	VSYNC
12	CSI1.HSYNC	I	P_SW4	HSYNC
13	GPIO3.5	O	P_SW4	Camera Trigger
14	STROBE	I		Strobe Signal from Camera (available only on solder pad)
15	NC	NC		Not Connected
16	NC	NC		Not Connected
17	CSI1.DO	I	P_SW4	Pixel Data
18	CSI1.D1	I	P_SW4	Pixel Data
19	VCAMIO	PWR	1V8	Camera IO Power Supply
20	GND	PWR	GND	Power Ground
21	CSI1.D2	I	P_SW4	Pixel Data
22	CSI1.D3	I	P_SW4	Pixel Data
23	CSI1.D4	I	P_SW4	Pixel Data
24	CSI1.D5	I	P_SW4	Pixel Data
25	GND	PWR	GND	Power Ground
26	CSI1.D6	I	P_SW4	Pixel Data
27	CSI1.D7	I	P_SW4	Pixel Data
28	CSI1.D8	I	P_SW4	Pixel Data
29	CSI1.D9	I	P_SW4	Pixel Data
30	CSI1.PWDN	O	P_SW4	Output Enable (Active Low)

Table 4-3: BLT-ISM-Connector interface description (X13)

## **5 Support**

### **5.1 General Support**

General support for products can be found at Bluetechnix' support site <https://support.bluetechnix.at/wiki>

### **5.2 Board Support Packages**

Board support packages, boot loaders and further software downloads can be downloaded at the products wiki page at <https://support.bluetechnix.at/wiki>

### **5.3 i.MX Software Support**

#### **5.3.1 Linux**

Linux BSP and images of derivatives can be found at Bluetechnix' support site <https://support.bluetechnix.at/wiki> at the software section of the related product.

#### **5.3.2 Win CE**

WinCE is only supported on ARM platforms. Please contact Bluetechnix for support information.

### **5.4 i.MX® Design Services**

Based on more than seven years of experience with Blackfin and i.MX, Bluetechnix offers development assistance as well as custom design services and software development.

#### **5.4.1 Upcoming Products and Software Releases**

Keep up to date with all product changes, releases and software updates of Bluetechnix at <http://www.bluetechnix.com>.

## 6 Ordering Information

### 6.1 Predefined mounting options for EXT-SBC-i.MX51-DISP

Article Number	Name	Description
100-2523-1	EXT-SBC-i.MX51-DISP	Display and camera extender board for SBC-i.MX51
100-9910-1	EDT-TFT-5.0"-WVGA-G-ET0500G0DH6	EDT Display TFT 5.0" WVGA, 300cd/m <sup>2</sup> LED, TTL, touch
100-4110-2	SBC-i.MX51-S-C-Q24S512N2048 (SBC-i.MX51)	Single-Board Computer SBC-I.MX51 based on i.MX51 SoC

Table 6-1: Ordering information

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**NOTE:** Custom hard and software developments are available on request! Please contact Bluetechnix ([office@bluetechnix.com](mailto:office@bluetechnix.com)) if you are interested in custom hard- and software developments.

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## 7 Dependability

### 7.1 MTBF

Please keep in mind that a part stress analysis would be the only way to obtain significant failure rate results, because MTBF numbers just represent a statistical approximation of how long a set of devices should last before failure. Nevertheless, we can calculate an MTBF of the development board using the bill of material. We take all the components into account. The PCB and solder connections are excluded from this estimation. For test conditions we assume an ambient temperature of 30°C of all development board components. We use the MTBF Calculator from ALD (<http://www.aldservice.com/>) and use the reliability prediction MIL-217F2 Part Stress standard. Please get in touch with Bluetechnix ([office@bluetechnix.com](mailto:office@bluetechnix.com)) if you are interested in the MTBF result.

## 8 Product History

### 8.1 Version Information

Version	Date	Changes
1.2	2011-05-30	Changed layout of Image Sensor Connector X13
1.1	2011-04-20	First release V1.1 of the Hardware.

Table 8-1: Overview product changes

### 8.2 Anomalies

Version	Date	Description
1.1	2011-04-20	No anomalies reported yet.

Table 8-2: Overview product anomalies

## 9 Document Revision History

Version	Date	Document Revision
3	2011 08 03	Changed product photos
2	2011 05 30	Update for Board Revision 1.2
1	2011 04 20	First release V1.0 of the Document

Table 9-1: Revision History

## 10 List of Abbreviations

Abbreviation	Description
<b>ADI</b>	Analog Devices Inc.
<b>AI</b>	Analog Input
<b>AMS</b>	Asynchronous Memory Select
<b>AO</b>	Analog Output
<b>CM</b>	Core Module
<b>DC</b>	Direct Current
<b>DSP</b>	Digital Signal Processor
<b>eCM</b>	Enhanced Core Module
<b>EBI</b>	External Bus Interface
<b>ESD</b>	Electrostatic Discharge
<b>GPIO</b>	General Purpose Input Output
<b>I</b>	Input
<b>I<sup>2</sup>C</b>	Inter-Integrated Circuit
<b>I/O</b>	Input/Output
<b>ISM</b>	Image Sensor Module
<b>LDO</b>	Low Drop-Out regulator
<b>MTBF</b>	Mean Time Between Failure
<b>NC</b>	Not Connected
<b>NFC</b>	NAND Flash Controller
<b>O</b>	Output
<b>OS</b>	Operating System
<b>PPI</b>	Parallel Peripheral Interface
<b>PWR</b>	Power
<b>RTOS</b>	Real-Time Operating System
<b>SADA</b>	Stand Alone Debug Agent
<b>SD</b>	Secure Digital
<b>SoC</b>	System on Chip
<b>SPI</b>	Serial Peripheral Interface
<b>SPM</b>	Speech Processing Module
<b>SPORT</b>	Serial Port
<b>TFT</b>	Thin-Film Transistor
<b>TISM</b>	Tiny Image Sensor Module
<b>TSC</b>	Touch Screen Controller
<b>UART</b>	Universal Asynchronous Receiver Transmitter
<b>USB</b>	Universal Serial Bus
<b>USBOTG</b>	USB On The Go
<b>ZIF</b>	Zero Insertion Force

Table 10-1: List of abbreviations



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Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



#### Как с нами связаться

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